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12-17-02
L. Spruill

Inventor(s): Tae Heon Lee et al.

U.S. Serial Number: 09/687,048

U.S. Filing Date: October 13, 2000

Title of Invention: LEADFRAME AND
SEMICONDUCTOR PACKAGE
WITH IMPROVED SOLDER
JOINT STRENGTH

Docket Number: 45475-00026

Commissioner for Patents
Washington, D.C. 20231

Dear Madam or Sir:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:

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on November 22, 2002

Type or Print Name *Carl H. Yoder*

Signature *Carl H. Yoder*

PROPOSED AMENDMENTS TO THE DRAWINGS

It is respectfully requested that the Examiner approve the following amendments to the Drawings of the above-identified application for patent:

1. Please approve the changes to the Drawings as indicated in red ink on the attached drawing sheet(s).
2. Please substitute the attached Formal Figures for the Informal Figures as originally filed.
3. Please add new Figure(s) for the Informal Figures to the application.



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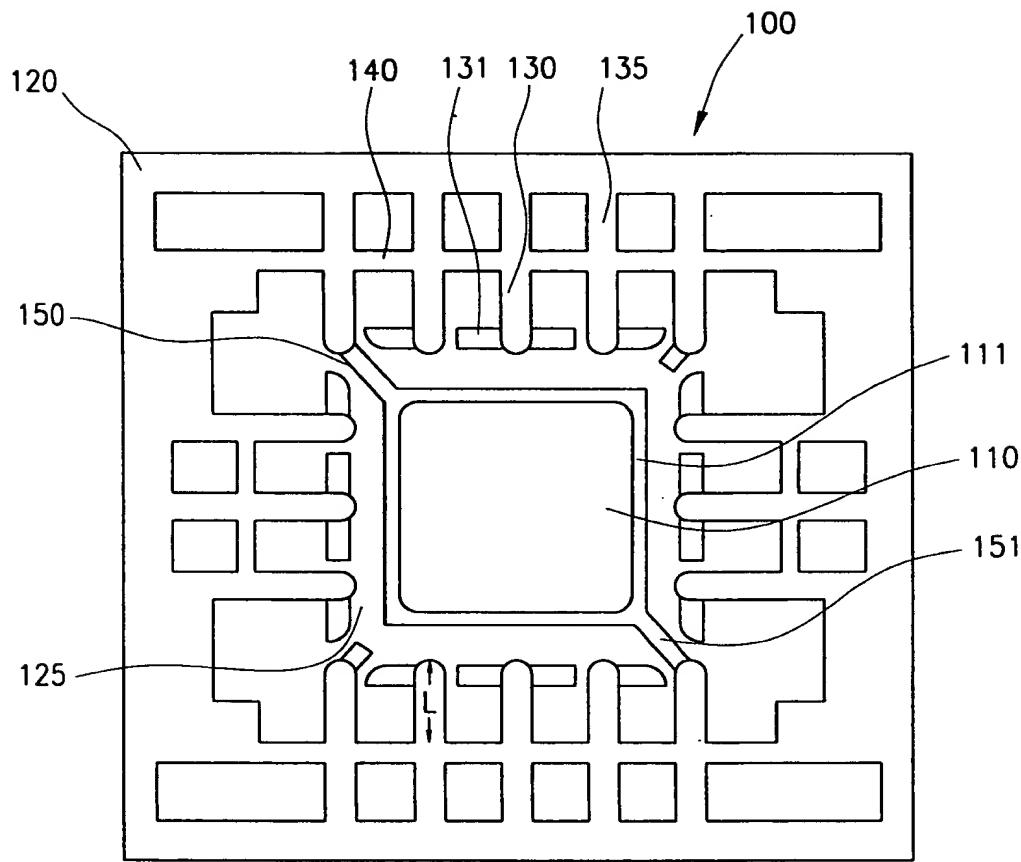


FIG. 1
(PRIOR ART)



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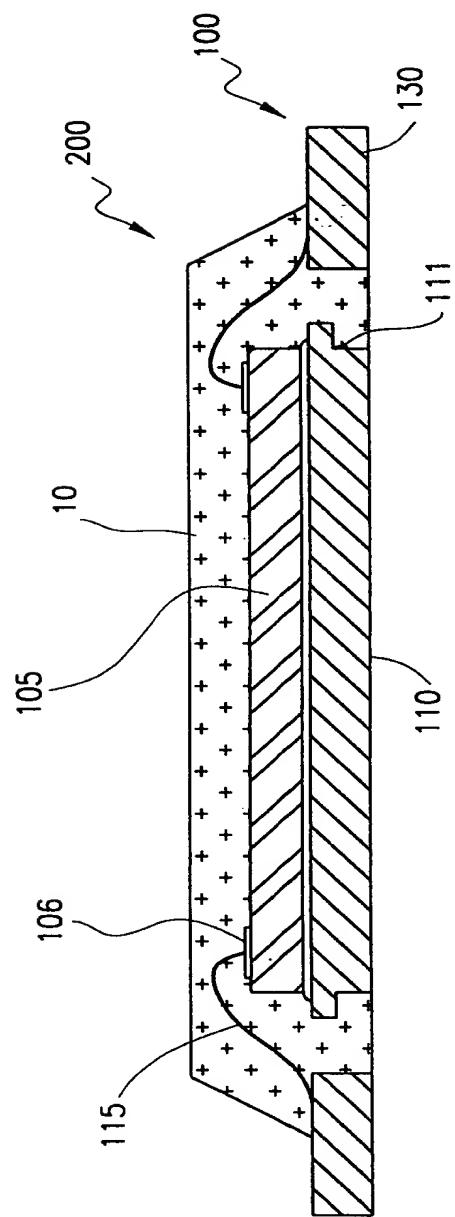


FIG. 2
(PRIOR ART)



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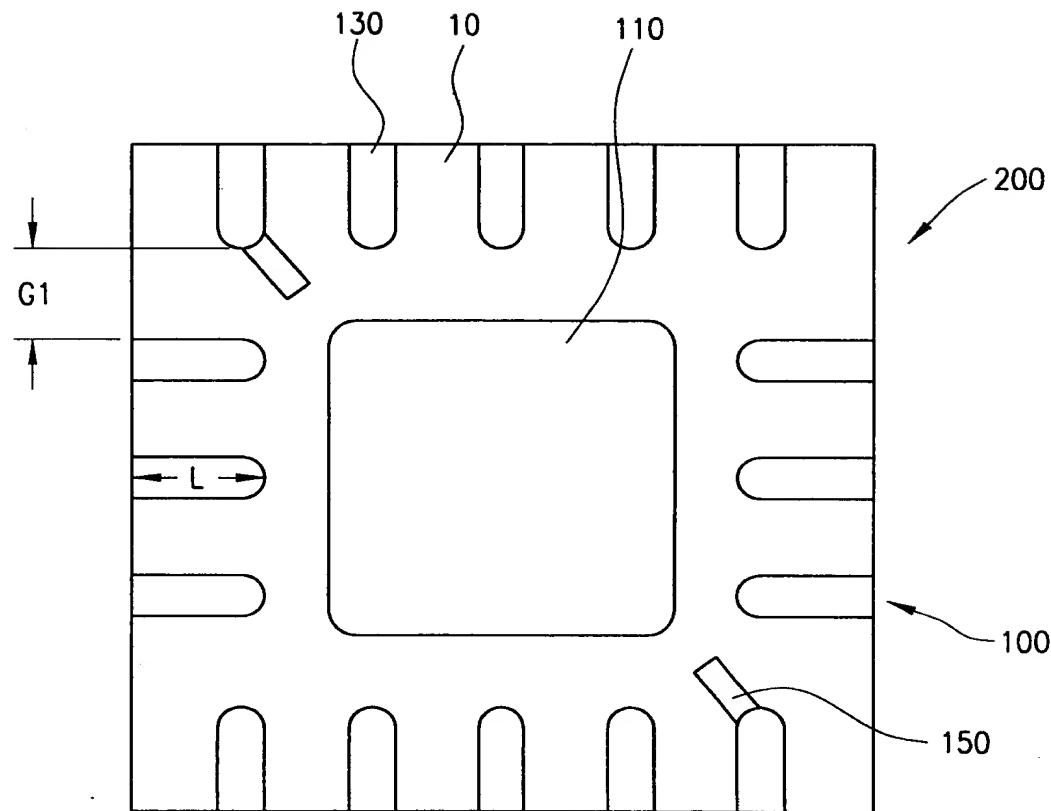


FIG. 3
(PRIOR ART)



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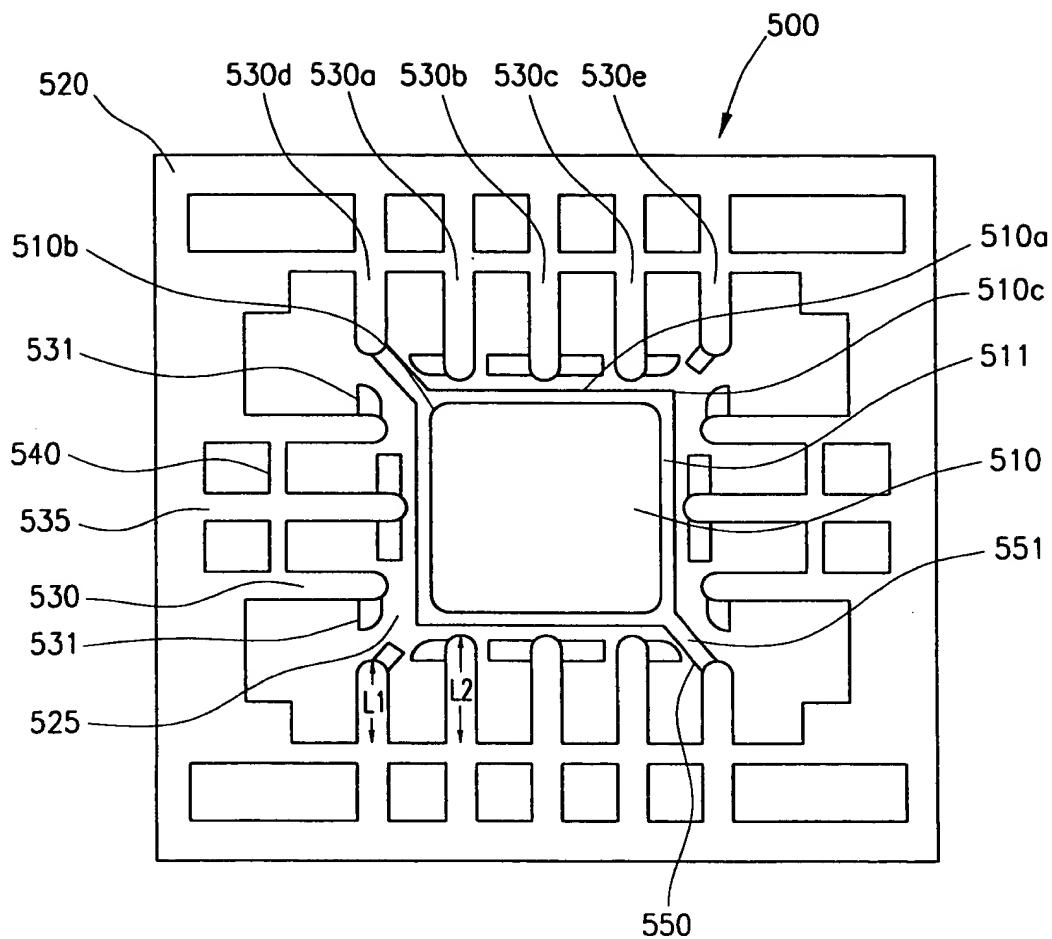


FIG. 4



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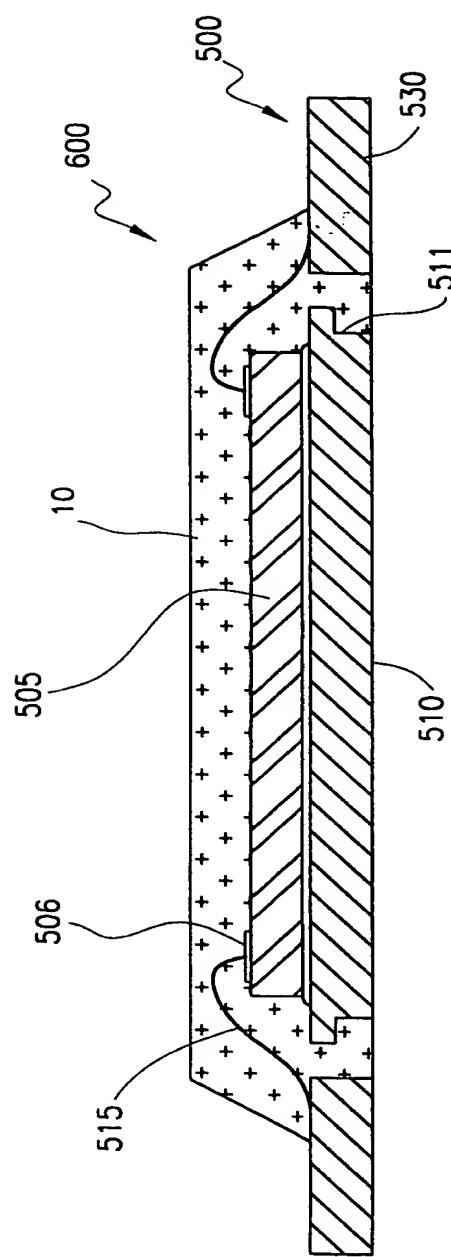


FIG. 5

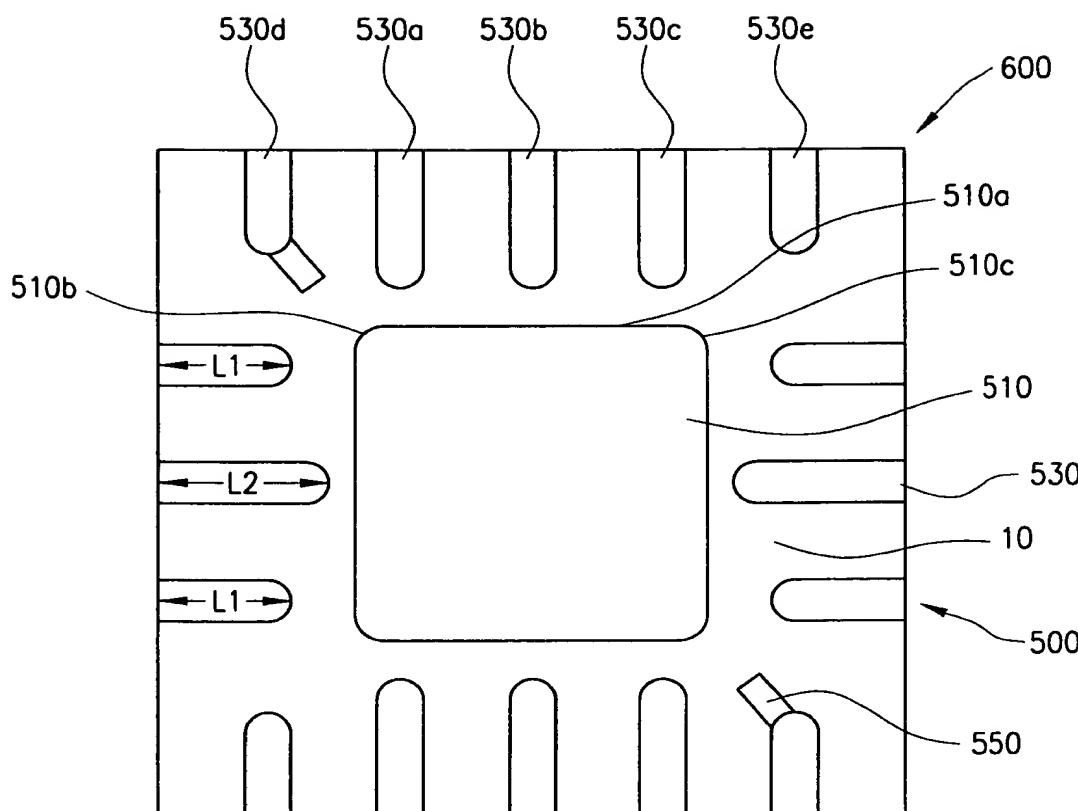


FIG. 6



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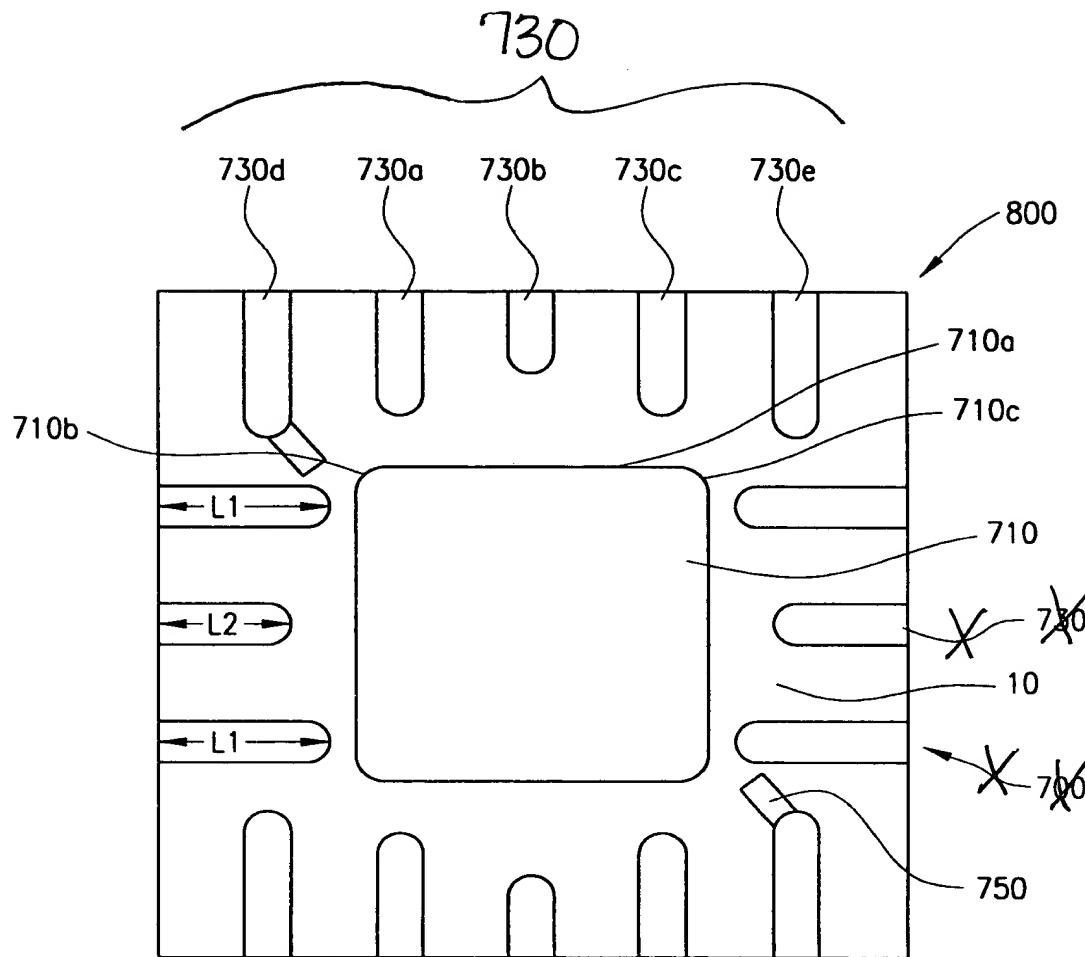


FIG. 7